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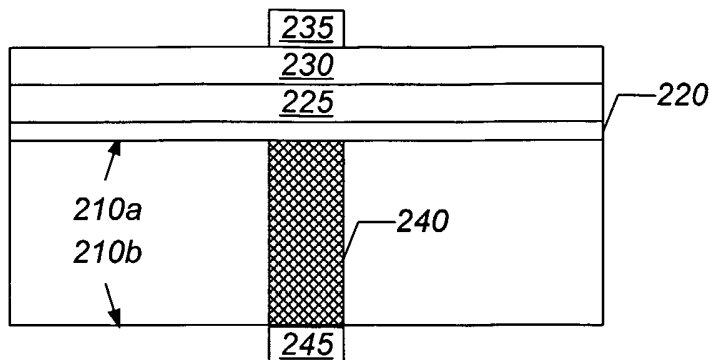
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(54) Title: LIGHT-EMITTING DEVICES HAVING AN ACTIVE REGION WITH ELECTRICAL CONTACTS COUPLED TO OPPOSING SURFACES THEREOF AND METHODS OF FORMING THE SAME



(57) Abstract: A light-emitting device comprises a substrate (205) that has a contact plug (240) extending therethrough between first and second opposing surfaces. An active region is on the first surface, a first electrical contact is on the active region, and a second electrical contact is adjacent to the second surface of the substrate. The contact plug couples the second electrical contact to the active region. Such a configuration may allow electrical contacts to be on opposing sides of a chip, which may increase the number of devices that may be formed on a wafer.

LIGHT-EMITTING DEVICES HAVING AN ACTIVE REGION WITH
ELECTRICAL CONTACTS COUPLED TO OPPOSING SURFACES THEREOF
AND METHODS OF FORMING THE SAME

Related Application

This application claims the benefit of and priority to U. S. Provisional Patent Application No. 60/466,617, filed April 30, 2003, the disclosure of which is hereby incorporated herein by reference as if set forth in its entirety.

5

Background of the Invention

The present invention relates generally to microelectronic devices and fabrication methods therefor, and, more particularly, to light-emitting devices and fabrication methods therefor.

Light-emitting diodes (LEDs) are widely used in consumer and commercial applications. As is well known to those skilled in the art, a light-emitting diode generally includes a diode region on a microelectronic substrate. The microelectronic substrate may comprise, for example, gallium arsenide, gallium phosphide, alloys thereof, silicon carbide, and/or sapphire. Continued developments in LEDs have resulted in highly efficient and mechanically robust light sources that can cover the visible spectrum and beyond. These attributes, coupled with the potentially long service life of solid state devices, may enable a variety of new display applications, and may place LEDs in a position to compete with well entrenched incandescent and fluorescent lamps.

Referring now to **FIG. 1**, a conventional GaN-based LED **100** comprises a sapphire (Al_2O_3) substrate **105** that has first and second opposing surfaces **110a** and **110b**, respectively, and may be at least partially transparent to optical radiation. A

diode region, comprising an n-type layer **115** and a p-type layer **120** is disposed on the second surface **110b** and is configured to emit optical radiation upon application of a voltage across the diode region, for example across ohmic contacts **130** and **135**.

The diode region including the n-type layer **115** and/or the p-type layer **125**
5 may comprise gallium nitride-based semiconductor layers, including alloys thereof, such as indium gallium nitride and/or aluminum indium gallium nitride. The fabrication of gallium nitride layers is known to those skilled in the art, and is described, for example, in U. S. Patent No. 6,177,688, the disclosure of which is hereby incorporated herein by reference. It will also be understood that a buffer layer
10 or layers comprising aluminum nitride, for example, may be provided between the n-type gallium nitride layer **115** and the sapphire substrate **105**, as described in U.S. Patents 5,393,993, 5,523,589, 6,177,688, and Application Serial No. 09/154,363 entitled *Vertical Geometry InGaN Light Emitting Diode*, the disclosures of which are hereby incorporated herein by reference. The n-type gallium nitride layer **115** may
15 comprise silicon-doped gallium nitride, while the p-type gallium nitride layer **120** may comprise magnesium-doped gallium nitride.

In some LEDs, the ohmic contact **135** for the p-type gallium nitride layer **120** comprises platinum, nickel and/or titanium/gold. In other LEDs, a reflective ohmic contact comprising, for example, aluminum and/or silver, may be used. The ohmic
20 contact **130** to the n-type gallium nitride layer **115** may comprise aluminum and/or titanium. Other suitable materials that form ohmic contacts to p-type gallium nitride and n-type gallium nitride may be used for ohmic contacts **135** and **130**, respectively. Examples of ohmic contacts to n-type gallium nitride layers and p-type gallium nitride layers are described, for example, in U.S. Patent 5,767,581, the disclosure of which is
25 hereby incorporated herein by reference.

Unfortunately, LED devices based upon a sapphire platform (*i.e.*, fabricated on a sapphire wafer) typically use two contacts (anode and cathode) on the same side of the chip, such as the diode region side shown in FIG. 1. This may constrain the total number of die on a wafer. In addition, the use of two top side contacts may impact
30 LED assemblers (*i.e.*, packaging) as two wire bonds may be made.

Summary of the Invention

According to some embodiments of the present invention, a light-emitting device comprises a substrate that has a contact plug extending therethrough between first and second opposing surfaces. An active region is on the first surface, a first electrical contact is on the active region, and a second electrical contact is adjacent to the second surface of the substrate. The contact plug couples the second electrical contact to the active region. Advantageously, such embodiments may allow electrical contacts to be on opposing sides of a chip, which may increase the number of devices that may be formed on a wafer.

10 In particular embodiments, an ohmic contact layer may be disposed between the first surface and the active region that comprises at least one of the following materials: TiN, platinum, nickel/gold, nickel oxide/gold, nickel oxide/platinum, Ti, and titanium/gold. The ohmic contact layer may also have a thickness between about 10Å and about 100 Å and may be at least partially transparent.

15 In further embodiments, the substrate comprises a non-conductive material, such as sapphire, and the contact plug comprises a conductive material, such as gold, silver, gold alloys, and/or silver alloys. The first electrical contact may comprise platinum, nickel, and/or titanium/gold. The second electrical contact may comprise aluminum and/or titanium.

20 In still other embodiments, a light-emitting device may be formed by forming an active region on a first substrate. A second substrate may also be provided in which a via may be formed between first and second opposing surfaces. A contact plug may then be formed in the via. The active region from the first substrate may be transferred to the second substrate. Advantageously, the second substrate, which may be viewed as a "surrogate" substrate, may be selected to have particular material properties that may enhance light extraction from the light-emitting device structure.

Brief Description of the Drawings

Other features of the present invention will be more readily understood from the following detailed description of specific embodiments thereof when read in conjunction with the accompanying drawings, in which:

FIG. 1 is a cross-sectional diagram that illustrates a conventional GaN-based light-emitting diode (LED);

FIGS. 2A - 2H are cross sectional diagrams that illustrate light-emitting devices and methods of forming same in accordance with various embodiments of the present invention; and

FIGS. 3 - 5 are flowcharts that illustrate exemplary operations for fabricating light-emitting devices in accordance with some embodiments of the present invention.

Detailed Description of Preferred Embodiments

While the invention is susceptible to various modifications and alternative forms, specific embodiments thereof are shown by way of example in the drawings and will herein be described in detail. It should be understood, however, that there is no intent to limit the invention to the particular forms disclosed, but on the contrary, the invention is to cover all modifications, equivalents, and alternatives falling within the spirit and scope of the invention as defined by the claims. Like numbers refer to like elements throughout the description of the figures. In the figures, the dimensions of layers and regions are exaggerated for clarity. Each embodiment described herein also includes its complementary conductivity type embodiment.

It will be understood that when an element such as a layer, region or substrate is referred to as being "on" another element, it can be directly on the other element or intervening elements may also be present. It will be understood that if part of an element, such as a surface, is referred to as "inner," it is farther from the outside of the device than other parts of the element. Furthermore, relative terms such as "beneath" or "overlies" may be used herein to describe a relationship of one layer or region to another layer or region relative to a substrate or base layer as illustrated in the figures. It will be understood that these terms are intended to encompass different orientations of the device in addition to the orientation depicted in the figures. Finally, the term "directly" means that there are no intervening elements. As used herein, the term "and/or" includes any and all combinations of one or more of the associated listed items.

It will be understood that, although the terms first, second, etc. may be used herein to describe various elements, components, regions, layers and/or sections, these elements, components, regions, layers and/or sections should not be limited by these terms. These terms are only used to distinguish one element, component, region, layer or section from another region, layer or section. Thus, a first region, layer or section

discussed below could be termed a second region, layer or section, and, similarly, a second without departing from the teachings of the present invention.

Embodiments of the present invention will now be described, generally, with reference to GaN-based light-emitting diodes (LEDs) on non-conductive substrates, such as, for example, sapphire (Al_2O_3)-based substrates. The present invention, however, is not limited to such structures. Embodiments of the invention may use other substrates, including conductive substrates. Accordingly, combinations can include an AlGaInP diode on a GaP substrate, a GaN diode on a SiC substrate, an SiC diode on an SiC substrate, an SiC diode on a sapphire substrate, and/or a nitride-based diode on a gallium nitride, silicon carbide, aluminum nitride, zinc oxide and/or other substrate. Moreover, the present invention is not limited to the use of a diode region as an active region. Other types of active regions may also be used in accordance with some embodiments of the present invention.

Examples of light-emitting devices that may be used in embodiments of the present invention include, but are not limited to, the devices described in the following U. S. Patent Nos.: 6,201,262, 6,187,606, 6,120,600, 5,912,477, 5,739,554, 5,631,190, 5,604,135, 5,523,589, 5,416,342, 5,393,993, 5,338,944, 5,210,051, 5,027,168, 5,027,168, 4,966,862 and/or 4,918,497, the disclosures of which are incorporated herein by reference. Other suitable LEDs and/or lasers are described in United States Patent Application Serial No. 10/140,796, entitled "GROUP III NITRIDE BASED LIGHT EMITTING DIODE STRUCTURES WITH A QUANTUM WELL AND SUPERLATTICE, GROUP III NITRIDE BASED QUANTUM WELL STRUCTURES AND GROUP III NITRIDE BASED SUPERLATTICE STRUCTURES", filed May 7, 2002, as well as United States Patent Application Serial No. 10/057,821, filed January 25, 2002 entitled "LIGHT EMITTING DIODES INCLUDING SUBSTRATE MODIFICATIONS FOR LIGHT EXTRACTION AND MANUFACTURING METHODS THEREFOR" the disclosures of which are incorporated herein as if set forth fully. Furthermore, phosphor coated LEDs, such as those described in United States Patent Application Serial No. 10/659,241 entitled "PHOSPHOR-COATED LIGHT EMITTING DIODES INCLUDING TAPERED SIDEWALLS, AND FABRICATION METHODS THEREFOR," filed September 9, 2003, the disclosure of which is incorporated by

reference herein as if set forth full, may also be suitable for use in embodiments of the present invention.

The LEDs and/or lasers may be configured to operate in a "flip-chip" configuration such that light emission occurs through the substrate. In such
5 embodiments, the substrate may be patterned so as to enhance light output of the devices as is described, for example, in United States Patent Application Serial No. 10/057,821, filed January 25, 2002 entitled "LIGHT EMITTING DIODES INCLUDING SUBSTRATE MODIFICATIONS FOR LIGHT EXTRACTION AND MANUFACTURING METHODS THEREFOR" the disclosure of which is
10 incorporated herein by reference as if set forth fully herein.

Referring now to **FIGS. 2A - 2H**, light-emitting devices and methods of forming same, in accordance with some embodiments of the present invention, will now be described. As shown in **FIG. 2A**, a substrate **205**, such as, for example, a sapphire substrate, is provided. A sapphire substrate is generally non-conductive;
15 however, as discussed above, conductive substrates may also be used in accordance with other embodiments of the present invention. The substrate **205** has a first surface **210a** and a second surface **210b** and may be at least partially transparent to optical radiation. An ohmic contact layer **220** may optionally be formed on the first surface **210a**. In accordance with various embodiments of the present invention, the ohmic
20 contact layer **220** may comprise TiN, platinum, nickel/gold, nickel oxide/gold, nickel oxide/platinum, Ti, titanium/gold and/or alloys thereof. The ohmic contact layer **220** may have a thickness between about 10Å and about 100 Å and may be at least partially transparent to optical radiation in accordance with some embodiments of the present invention.

25 Referring now to **FIGS. 2B and 2C**, an active region, such as, for example, a diode region comprising an n-type layer **225** and a p-type layer **230** may be epitaxially grown on the ohmic contact layer **220**. The diode region, including the n-type layer **225** and/or the p-type layer **230** may comprise gallium nitride-based semiconductor layers, including alloys thereof, such as indium gallium nitride and/or aluminum
30 indium gallium nitride. The fabrication of gallium nitride layers is described, for example, in the above-incorporated U.S. Patent 6,177,688. A buffer layer or layers comprising aluminum nitride, for example, may be provided between the n-type gallium nitride layer **225** and the substrate **205**, as described in the above-incorporated

U.S. Patents 5,393,993, 5,523,589, 6,177,688, and Application Serial No. 09/154,363 entitled *Vertical Geometry InGaN Light Emitting Diode*. The n-type gallium nitride layer **225** may comprise silicon-doped gallium nitride, while the p-type gallium nitride layer **230** may comprise magnesium-doped gallium nitride.

5 Referring now to **FIG. 2D**, a first electrical contact **235** is formed on the diode region as shown. The first electrical contact **235** for the p-type gallium nitride layer **230** may comprise platinum, nickel, titanium/gold and/or alloys thereof. In other embodiments, a reflective electrical contact comprising, for example, aluminum and/or silver, may be used. Other suitable materials that form ohmic contact to p-type
10 gallium nitride may be used for the first electrical contact **235**. Examples of ohmic contacts to p-type gallium nitride layers are described, for example, in the above-incorporated U.S. Patent 5,767,581.

Referring now to **FIG. 2E**, a via is formed in the substrate **205** between the first and second surfaces **210a** and **210b**, respectively. In some embodiments, the via
15 may be formed by etching the substrate **205** using the ohmic contact layer **220** as an etch stop layer. Various etching techniques may be used in accordance with different embodiments of the present invention, including, but not limited to, wet etching, dry etching, and micro-machining. In particular embodiments of the present invention, the via may be formed in substantial alignment with the first electrical contact **235** to
20 reduce light loss due to "shading." In other embodiments, the via may be formed so that the via and the first electrical contact **235** are offset from one another. The offset configuration may be used to reduce stress on the gallium nitride-based layers **225** and **230**.

Referring now to **FIG. 2F**, a contact plug **240** is formed in the via by, for
25 example, plating the via with a conductive material, such as gold, silver, gold alloys, and/or silver alloys, in accordance with some embodiments of the present invention.

Referring now to **FIG. 2G**, a second electrical contact **245** is formed adjacent to the second surface **210b** such that the contact plug **240** couples the second electrical contact **235** to the ohmic contact layer **220**. Advantageously, because the ohmic
30 contact layer **220** contacts the n-type gallium nitride layer **225** across a relatively broad surface area, improved current spreading may be provided. The second electrical contact **245** for the n-type gallium nitride layer **225** may comprise

aluminum, titanium, and/or alloys thereof. Other suitable materials that form ohmic contact to n-type gallium nitride may be used for the second electrical contact **245**. Examples of ohmic contacts to n-type gallium nitride layers are described, for example, in the above-incorporated U.S. Patent 5,767,581. **FIG. 2H** shows the structure of **FIG. 2G** inverted with the diode region on top of the substrate **205**.

Although described above with respect to non-conductive substrate embodiments, conductive substrates, such as SiC substrates, may also be used in accordance with other embodiments of the present invention. In such embodiments, a high resistivity SiC substrate may be used to reduce parasitic (free carrier) absorption. In addition, the forward biased diode offset voltage may be reduced by reducing the heterobarrier between the n-type SiC substrate and the n-type GaN layer.

Exemplary operations for forming light-emitting devices, in accordance with some embodiments of the present invention, will now be described with reference to the flowcharts of **FIGS. 3 - 5**. Referring now to **FIG. 3**, operations begin at block **300** where a first substrate is provided. A diode region is formed on a surface of the first substrate at block **305** as described above with reference to **FIGS. 2B** and **2C**. An electrical contact may then be formed on the diode region at block **310** as described above with reference to **FIG. 2D**.

Referring now to **FIG. 4**, additional operations, which may be performed in parallel with the operations of **FIG. 3**, begin at block **400** where a second substrate is provided. An ohmic contact/etch stop layer may be formed on the second substrate as described above with reference to **FIG. 2A**. A via is then be formed in the second substrate at block **410** using, for example, the ohmic contact layer as an etch stop layer as described above with reference to **FIG. 2E**. At block **415**, the via may be filled with a conductive material to form a contact plug as described above with reference to **FIG. 2F**. An electrical contact may then be formed on the contact plug at block **420** as described above with reference to **FIG. 2G**.

Referring now to **FIG. 5**, the diode region and the electrical contact disposed thereon is transferred from the first substrate to the second substrate, such that the diode region is disposed on the ohmic contact layer at block **500**. Advantageously, the second substrate, which may be viewed as a "surrogate" substrate, may be selected to have particular material properties that may enhance light extraction from the light-emitting device structure.

Embodiments of the invention have been described above in which a diode is shown as an example of an active region. It should be understood, however, that an active region may include, but is not limited to, quantum wells, heterojunctions, homojunctions, multiple layers, combinations of the foregoing, or the like, in accordance with some embodiments of the present invention. For example, layers **225** and **230** may be embodied as described in the above-referenced patents and/or applications. Moreover, additional layers, such as lattice strain layers, may also be incorporated in light-emitting devices in accordance with further embodiments of the present invention.

10 In concluding the detailed description, it should be noted that many variations and modifications can be made to the preferred embodiments without substantially departing from the principles of the present invention. All such variations and modifications are intended to be included herein within the scope of the present invention, as set forth in the following claims.

15

Claims

That which is claimed:

1. A light-emitting device, comprising:
a substrate having a contact plug extending therethrough between first and
5 second opposing surfaces;
an active region on the first surface;
a first electrical contact on the active region; and
a second electrical contact adjacent to the second surface, the contact plug
coupling the second electrical contact to the active region.
10
2. The light-emitting device of Claim 1, further comprising:
an ohmic contact layer between the first surface and the active region.
3. The light-emitting device of Claim 2, wherein the ohmic contact layer
15 comprises at least one of TiN, platinum, nickel/gold, nickel oxide/gold, nickel
oxide/platinum, Ti, and titanium/gold.
4. The light-emitting device of Claim 2, wherein the ohmic contact layer
has a thickness between about 10Å and about 100 Å.
20
5. The light-emitting device of Claim 1, wherein the substrate comprises
sapphire.
6. The light-emitting device of Claim 1, wherein the contact plug
25 comprises gold, silver, a gold alloys, and/or a silver alloy.
7. The light-emitting device of Claim 1, wherein the first and second
electrical contacts are substantially aligned with respect to each other.
- 30 8. The light-emitting device of Claim 1, wherein the first and second
electrical contacts are offset with respect to each other.

9. The light-emitting device of Claim 1, wherein the active region comprises:

an n-type layer on the the first surface; and

a p-type layer on the n-type layer.

5

10. The light-emitting device of Claim 9, wherein the first electrical contact comprises at least one of platinum, nickel, and titanium/gold.

11. The light-emitting device of Claim 9, wherein the second electrical
10 contact comprises at least one of aluminum and titanium.

12. The light-emitting device of Claim 9, wherein the n-type layer comprises GaN.

13. The light emitting device of Claim 9, wherein the p-type layer
15 comprises GaN.

14. The light-emitting device of Claim 1, wherein the ohmic contact layer
is at least partially transparent.

20

15. A method of forming a light-emitting device, comprising:
forming an active region on a first surface of a substrate having first and
second opposing surfaces;
forming a via in the substrate between the first and second opposing surfaces;
25 forming a contact plug in the via;
forming a first electrical contact on the active region; and
forming a second electrical contact adjacent to the second surface that is
coupled to the active region by the contact plug.

16. The method of Claim 15, further comprising:
30 forming an ohmic contact layer between the first surface and the active region.

17. The method of Claim 15, wherein forming the active region comprises:

forming an n-type layer on the first surface; and
forming a p-type layer on the n-type layer.

18. The method of Claim 15, wherein forming the via comprises:
5 etching the substrate using the ohmic contact layer as an etch stop.

19. The method of Claim 18, wherein etching the substrate is performed
using at least one of the following etching techniques: wet etching, dry etching, and
micro-machining.

10

20. The method of Claim 15, wherein forming the via comprises:
forming the via in substantial alignment with the first electrical contact.

21. The method of Claim 15, wherein forming the via comprises:
15 forming the via such that the via and the first electrical contact are offset with
respect to each other.

22. The method of Claim 15, wherein forming the contact plug comprises:
plating the via with gold, silver, a gold alloy, and/or a silver alloy.

20

23. A method of forming a light-emitting device, comprising:
forming an active region on a first substrate;
forming a via between first and second opposing surfaces in a second
substrate;
25 forming a contact plug in the via; and
transferring the active region from the first substrate to the second substrate so
as to be disposed on the first surface.

24. The method of Claim 23, wherein forming the active region comprises:
30 forming an n-type layer on the first substrate; and
forming a p-type layer on the n-type layer.

25. The method of Claim 23, further comprising:

forming an ohmic contact layer between the first surface and the active region;

26. The method of Claim 25, wherein forming the via comprises:
etching the second substrate using the ohmic contact layer as an etch stop.

5

27. The method of Claim 26, wherein etching the second substrate is
performed using at least one of the following etching techniques: wet etching, dry
etching, and micro-machining.

10 28. The method of Claim 23, wherein forming the contact plug comprises:
plating the via with gold, silver, a gold alloy, and/or a silver alloy.

29. The method of Claim 23, further comprising:
forming a first electrical contact on the active region; and
15 forming a second electrical contact that is coupled to the contact plug at the
second surface.

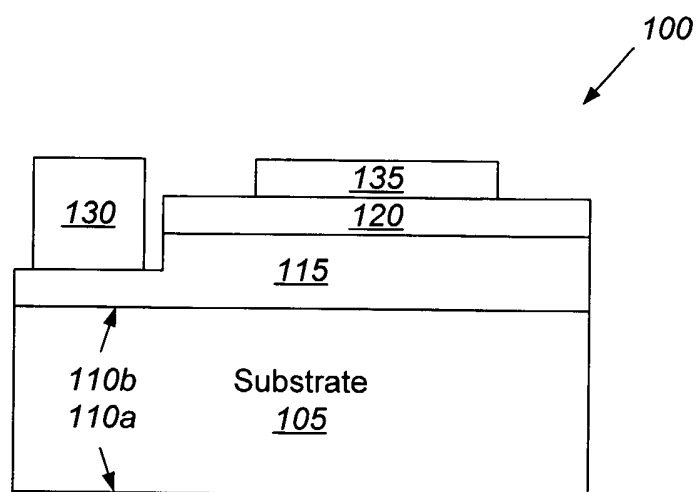


FIG. 1
(PRIOR ART)

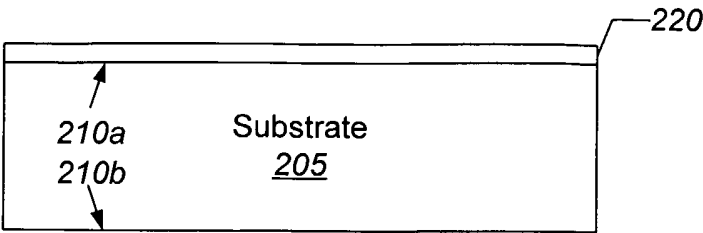


FIG. 2A

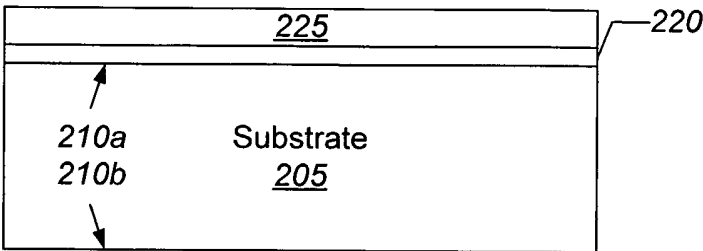


FIG. 2B

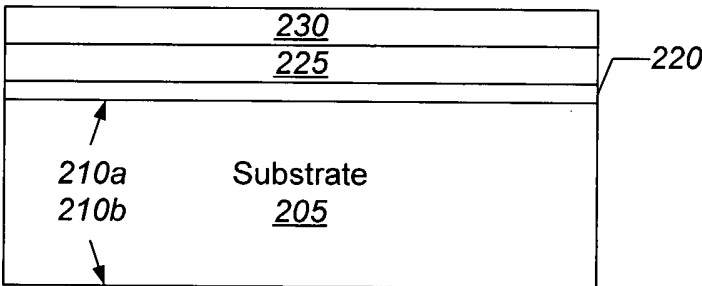


FIG. 2C

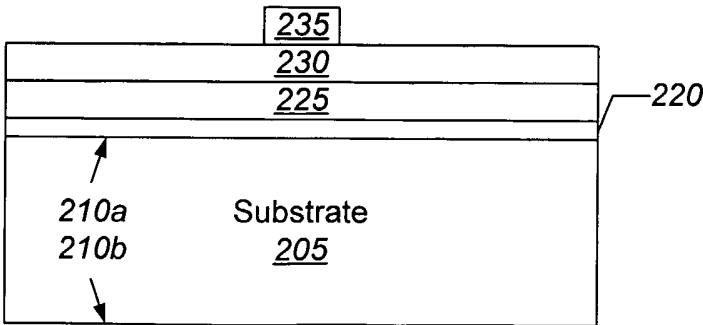
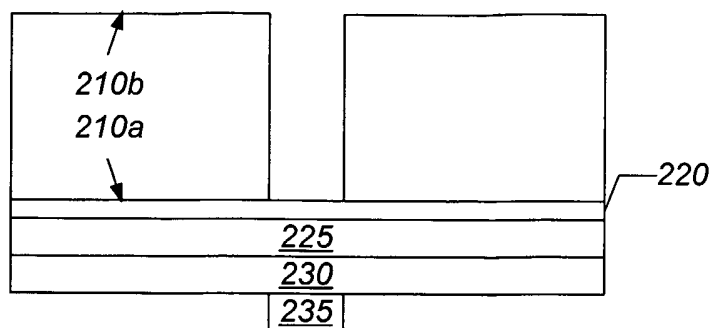
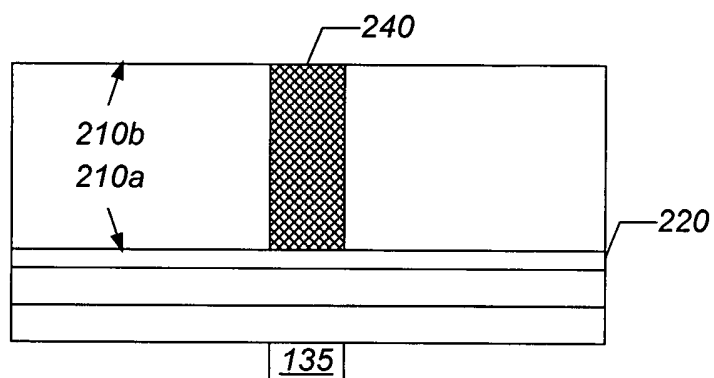
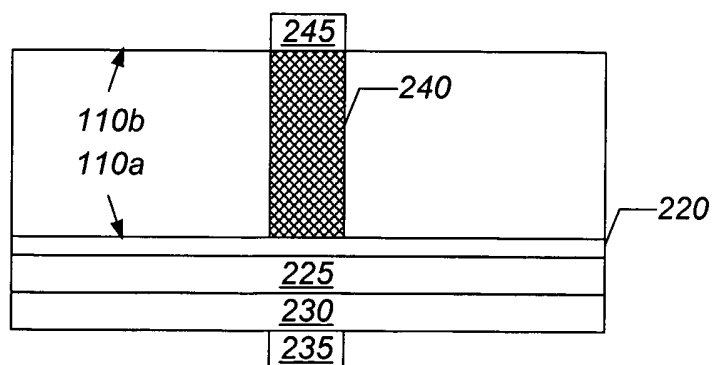
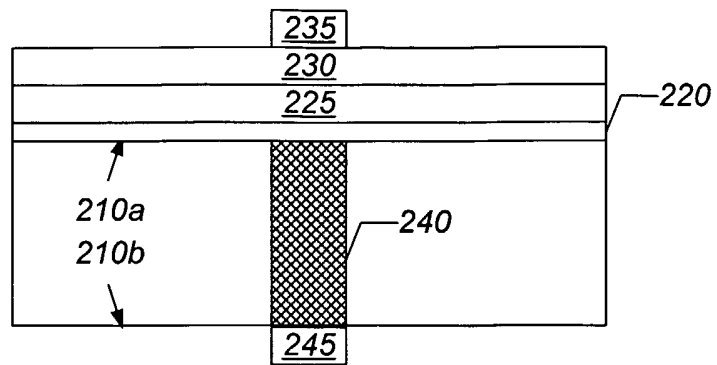
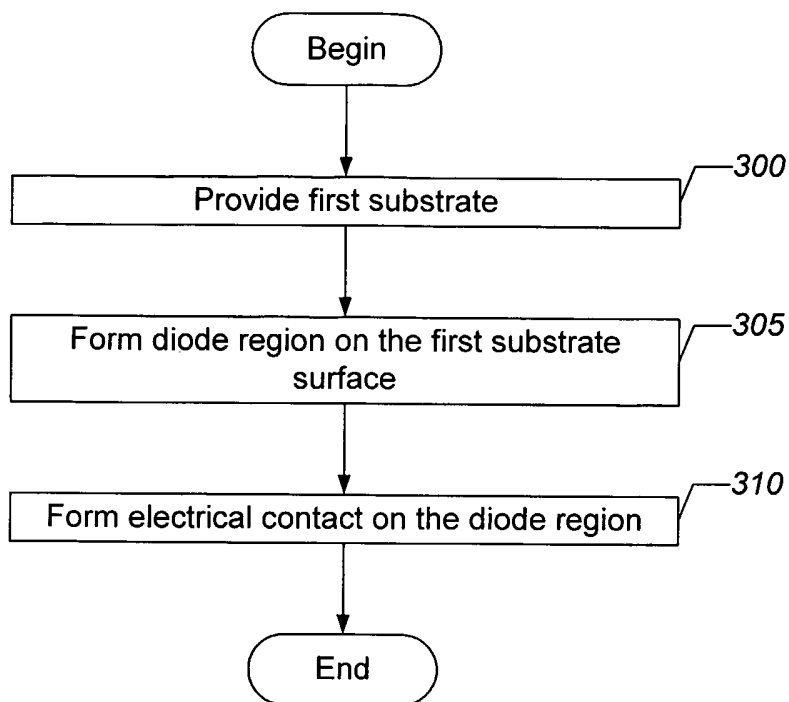
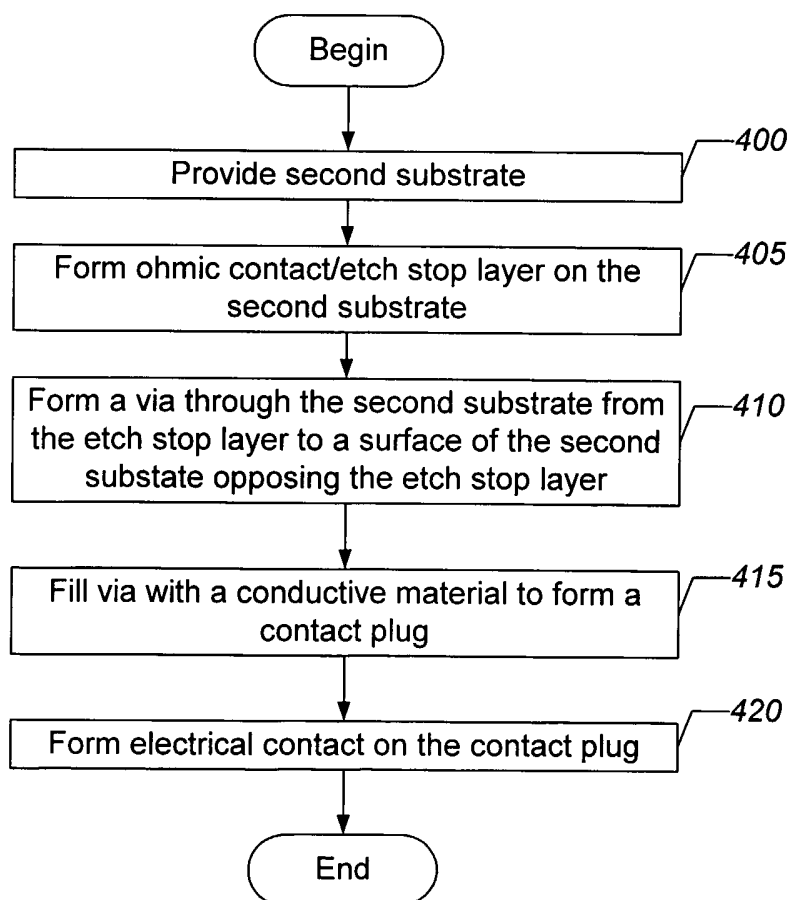
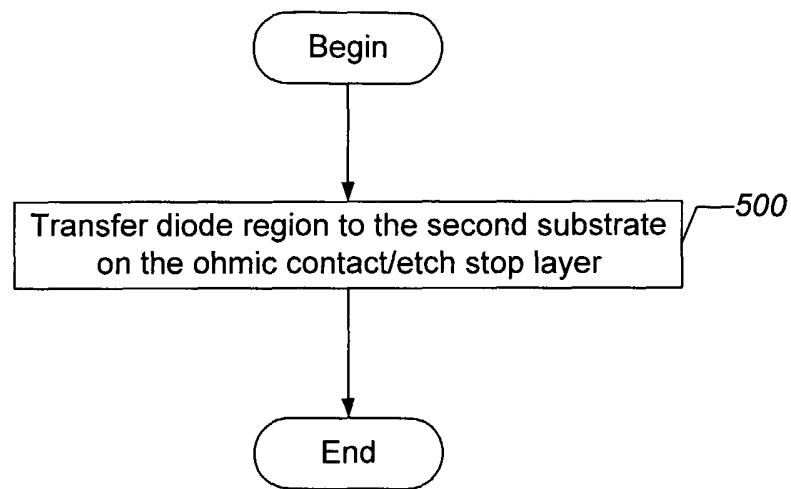


FIG. 2D

**FIG. 2E****FIG. 2F****FIG. 2G**

**FIG. 2H**

**FIG. 3****FIG. 4**

**FIG. 5**

INTERNATIONAL SEARCH REPORT

In International Application No
PCT/US2004/011358

A. CLASSIFICATION OF SUBJECT MATTER

IPC 7 H01L33/00

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

IPC 7 H01L

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practical, search terms used)

EP0-Internal

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category °	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
A	US 5 523 589 A (DMITRIEV VLADIMIR ET AL) 4 June 1996 (1996-06-04) cited in the application column 5, lines 9-17, Fig. 1 -----	1-29
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Date of the actual completion of the international search

30 August 2004

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C.(Continuation) DOCUMENTS CONSIDERED TO BE RELEVANT

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